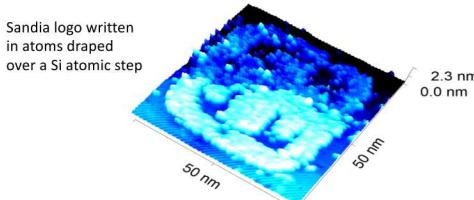


Atomic precision advanced manufacturing

Overview of capability & application opportunities

- Full fabrication & characterization of Si electronic devices with deterministic atom-precision features
- Quantum materials & digital devices at the physical limit of atom precision
- Structure-function relationships in thin-film materials for quantum electronics
- Atomic-resolution imaging & lithography via two scanning tunneling microscopes (STMs) with Si and Ge thin-film epitaxy (MBE)
- 1st/only user lab in world offering atom fab

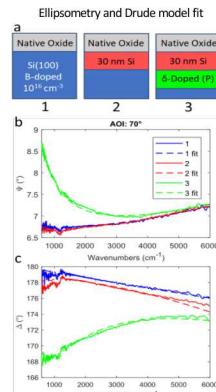


Capability POC: Ezra Bussmann (ebussma@sandia.gov)

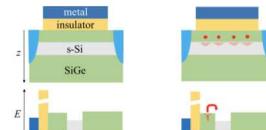
Examples of some recent results

- First demo mid-IR ellipsometry of atomic-precision doped Si material
- Drude model fits both optical & electronic response, reasonable agreement between approaches
- Electron density $n = 7.2 \times 10^{13} \text{ cm}^2$ mobility $\mu = 77 \text{ cm}^2/\text{Vs}$
- Optical method cuts materials characterization cost, provides input for future optoelectronics apps

Assessing adsorbate-based delta doping of Si with mid-IR ellipsometry
Advanced Functional Materials, forthcoming issue on atom fab (submitted)

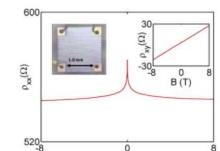


- First demo atomic-precision recipe for SiGe strained-layer materials
- Opens door to new quantum device engineering concepts utilizing remote doping in pristine heterostructure, e.g. tailored band structure via doping



Atomic-layer doping of SiGe heterostructures for atomic-precision donor devices, *Phys. Rev. Materials* 2, 066004 (2018) arXiv:1710.06449

Hall transport characterization of Si/SiGe heterostructure with atomic-layer doping

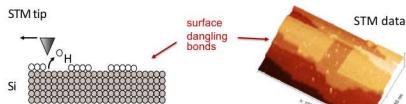


Longitudinal magnetoresistance and Hall (inset) resistance at $T = 0.3 \text{ K}$ of an atomic-layer doped Si/SiGe heterostructure along with a photo of the test device. The aluminum contact pads appear bright gold hue.

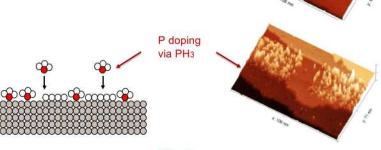
Detail of capability - atomic precision Si device fabrication & characterization

Fabrication recipe for Si nanoelectronic devices

1. Atomic-precision litho template on Si surface



2. Atomic-precision doping via template



3. Si cap



4. Fab electrical contact metal

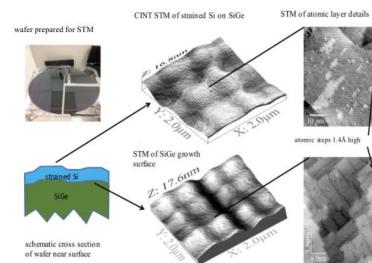


Device & material characterization at CINT

- Magnetoelectronic transport -Tzu Ming Lu, Tom Harris, or Mike Lilly
- Optical response- Willie Luk

Detail of associated capability - surface characterization

- Classical physics- structure and electronic properties of surfaces and thin films
- Quantum electronics- structure-function relationship in thin film heterostructure materials



- Interface roughness and atomic-steps strongly influence quantum coherence in Si/ SiGe devices
- Surface imaging in CINTs atomic-precision lab provided feedback to inform development of new semiconductor growth process at one manufacturer

Recent users & publications

Assessing adsorbate-based delta doping of Si with mid-IR ellipsometry
Advanced Functional Materials, forthcoming issue on atom fab

Atomic-layer doping of SiGe heterostructures for atomic-precision donor devices, *Phys. Rev. Materials* 2, 066004 (2018) arXiv:1710.06449

All-optical lithography fabrication process for contacting atomically-precise devices, *Appl. Phys. Lett.* 111, 193101 (2017) arXiv: 1708.05411

Heterogenous nucleation of pits via step pinning during Si(100) homoepitaxy, *New J. Phys.* 19, 113023 (2017) arXiv:1706.05127

Determining the resolution of scanning microwave impedance microscopy using buried atomic-precision donor structures, *Appl. Surf. Sci.* 423, 1097 (2017)

Users: National Institute of Standards and Technology, University of Maryland, University of Wisconsin-Madison, Intel Inc, Zvex Labs Inc